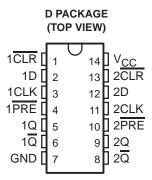
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- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- † Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- 4.5-V to 5.5-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 10.5 ns at 5 V
- Inputs Are TTL-Voltage Compatible



### description/ordering information

The SN74ACT74-EP is a dual positive-edge-triggered D-type flip-flop.

A low level at the preset (PRE) or clear (CLR) input sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup-time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at D can be changed without affecting the levels at the outputs.

#### ORDERING INFORMATION

TA	PACKAG	GE+ PART NUMBER MAR	TOP-SIDE MARKING	
-55°C to 125°C	SOIC - D	Tape and reel	SN74ACT74MDREP	SACT74MEP

<sup>&</sup>lt;sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

# FUNCTION TABLE (each flip-flop)

	INP	OUTI	OUTPUTS		
PRE	CLR	CLK	D	Q	Q
L	Н	Х	Χ	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	Н§	н§
Н	Н	$\uparrow$	Н	Н	L
Н	Н	$\uparrow$	L	L	Н
Н	Н	L	Χ	Q <sub>0</sub>	$\overline{Q}_0$

<sup>§</sup> This configuration is nonstable; that is, it does not persist when either PRE or CLR returns to its inactive (high) level.



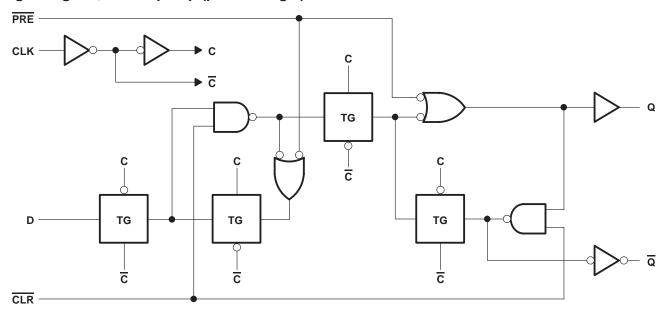
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# SN74ACT74-EP DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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### logic diagram, each flip-flop (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±200 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2)	86°C/W
Storage temperature range, T <sub>stg</sub> (see Note 3)	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
  - 3. Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep\_quality for additional information on enhanced plastic packaging.



# SN74ACT74-EP DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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### recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
$V_{IH}$	High-level input voltage	2		V
$V_{IL}$	Low-level input voltage		0.8	V
VI	Input voltage	0	VCC	V
VO	Output voltage	0	VCC	V
ЮН	High-level output current		-24	mA
loL	Low-level output current		24	mA
Δt/Δν	Input transition rise or fall rate		8	ns/V
TA	Operating free-air temperature	-55	125	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS		T	A = 25°C	;	MINI	88 A V	LIMIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
	- 50 A	4.5 V	4.4	4.49		4.4		
.,	IOH = -50 μA	5.5 V	5.4	5.49		5.4		,,
Voн	04 m4	4.5 V	3.86			3.7		V
	I <sub>OH</sub> = -24 mA	5.5 V	4.86			4.7		i
	In. 50 A			0.001	0.1		0.1	
.,,	I <sub>OL</sub> = 50 μA	5.5 V		0.001	0.1			
VOL	I <sub>OL</sub> = 24 mA				0.36		0.5	V
					0.36		0.5	
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		40	μΑ
ΔlCC <sup>†</sup>	One input at 3.4 V, Other inputs at GND or V <sub>CC</sub>	5.5 V		0.6			1.6	mA
Ci	$V_I = V_{CC}$ or GND	5 V		3				pF

<sup>†</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or VCC.

# timing characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				25°C				
			MIN MAX		MIN	MAX	UNIT	
fclock	Clock frequency			145		85	MHz	
4 Dulas duration	Delega describes	PRE or CLR low	5		7			
t <sub>W</sub>	Pulse duration	CLK	5		7		ns	
		Data	3		4			
t <sub>su</sub>	Setup time, data before CLK↑		0		0.5		ns	
th	Hold time, data after CLK↑		1		1		ns	



# SN74ACT74-EP DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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# switching characteristics over recommended operating free-air temperature (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	T,	T <sub>A</sub> = 25°C			BAAV	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
f <sub>max</sub>			145	210		85		MHz
<sup>t</sup> PLH	PRE or CLR	0	1	5.5	9.5	1	11.5	
<sup>t</sup> PHL	PRE OF CLR	Q or Q	1	6	10	1	12.5	ns
<sup>t</sup> PLH	CLK	Q or Q	1	7.5	11	1	14	20
<sup>t</sup> PHL	OLK .	QUIQ	1	6	10	1	12	ns

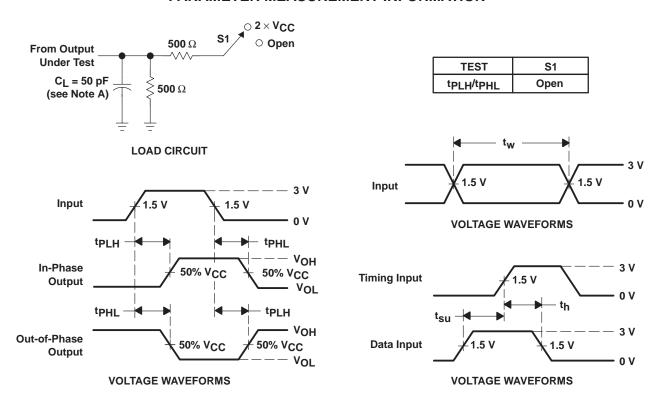
# operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	C <sub>L</sub> = 50 pF, f = 1 MHz	45	pF



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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_Q = 50~\Omega$ ,  $t_f \leq 2.5~\text{ns}$ ,  $t_f \leq 2.5~\text{ns}$ .
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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#### PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74ACT74MDREP	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SACT74MEP
SN74ACT74MDREP.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SACT74MEP
V62/04725-01XE	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SACT74MEP

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF SN74ACT74-EP:

Catalog: SN74ACT74

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

## PACKAGE OPTION ADDENDUM

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Military: SN54ACT74

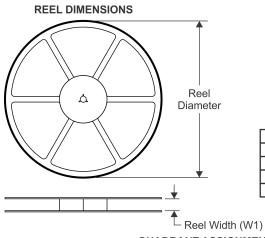
NOTE: Qualified Version Definitions:

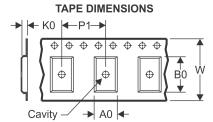
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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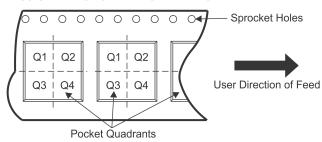
### TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

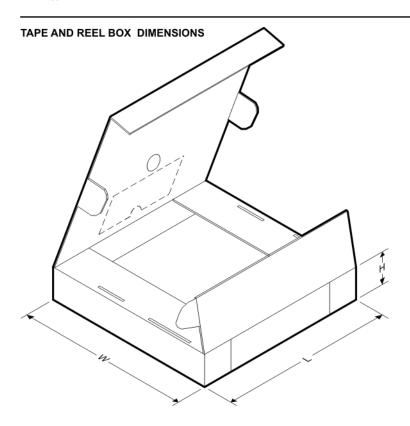
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT74MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

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#### \*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
I	SN74ACT74MDREP	SOIC	D	14	2500	340.5	336.1	32.0

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